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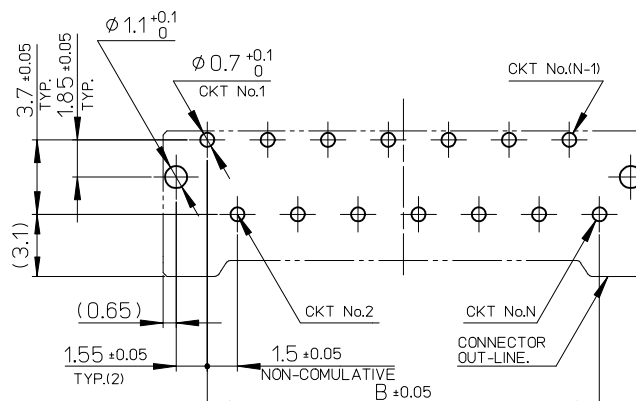
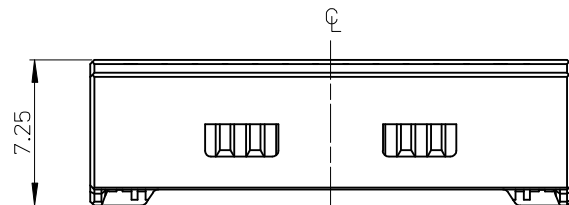
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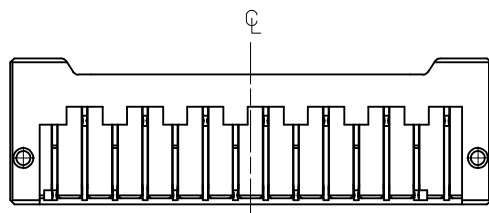
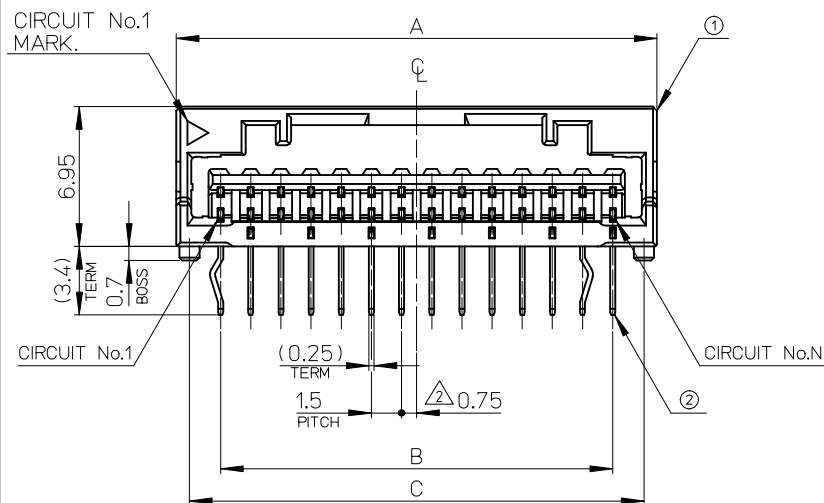
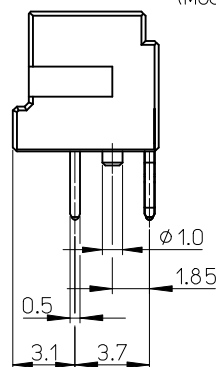
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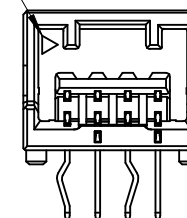


基板取付穴推奨寸法(マウント面)
RECOMMENDED P.C.BOARD
HOLE DIMENSION
(MOUNTING SIDE)
(t=1.6)



No.	部品 PART	材料 MATERIAL
①	ハウジング HOUSING	ポリアミド(PA) UL94V-0 POLYAMIDE UL94V-0 色: 注記 5. 参照 COLOR: SEE NOTES 5.
②	ターミナル TERMINAL	銅合金 COPPER ALLOY テール部: 錫めっき TAIL AREA: TIN PLATING 下地: ニッケルめっき(1.0μm以上) UNDER PLATING: NICKEL (1.0 MICROMETER MINIMUM)

CIRCUIT No.1
MARK.



2~11極 CIRCUIT NO.1
CIRCUIT No.1 OF 2-11 CIRCUIT

26.8	24.1	21	25.4	503175-150*	15
25.3	22.6	19.5	23.9	503175-140*	14
23.8	21.1	18	22.4	503175-130*	13
22.3	19.6	16.5	20.9	503175-120*	12
20.8	18.1	15	19.4	503175-110*	11
19.3	16.6	13.5	17.9	503175-100*	10
17.8	15.1	12	16.4	503175-090*	9
16.3	13.6	10.5	14.9	503175-080*	8
14.8	12.1	9	13.4	503175-070*	7
13.3	10.6	7.5	11.9	503175-060*	6
11.8	9.1	6	10.4	503175-050*	5
10.3	7.6	4.5	8.9	503175-040*	4
8.8	6.1	3	7.4	503175-030*	3
7.3	4.6	1.5	5.9	503175-020*	2
D	C	B	A	TRAY PACKAGE ORDER NO.	CIRCUIT

REVISED EC NO: J2009-2905 DRAWN: TODA CHKD: S. MARIYAMA APPR: S. CHIKAWA	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY NNISHI	DATE 2008/06/06	TITLE 1.5 W/B SINGLE DIP R/A REC.ASSY 2-15CKT			
		10 OVER 30 UNDER	± 0.25	CHECKED BY KASAKAWA	DATE 2008/06/06				
		30 OVER	± 0.3	APPROVED BY SICHIKAWA	DATE 2008/06/06	 MOLEX INCORPORATED			
		ANGULAR ±3 °		MATERIAL NO.					DOCUMENT NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-503175-001			1 OF 2
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

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